



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT

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JAN 24 2003

TC 1700

Applicant: Wood et al.

Serial No.: 10/007,288

Examiner: Mercado, Julian A.

Filed: December 3, 2001

Group Art Unit: 1745

For: METHOD OF MAKING A WAFER-PAIR HAVING SEALED CHAMBERS

Atty. Docket No.: H16-17400 (1100.1138101)

INFORMATION DISCLOSURE STATEMENT BEFORE  
MAILING DATE OF EITHER A FINAL ACTION OR NOTICE  
OF ALLOWANCE (37 CFR 1.97(c))

Assistant Commissioner for Patents  
Washington, D.C. 20231

<p><b>CERTIFICATE UNDER 37 C.F.R. 1.8:</b> I hereby certify that this correspondence is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231, on this <u>14</u> day of <u>January</u>, 2003.</p> <p>By <u>Brian N. Tufte</u></p>
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Dear Sir:

Pursuant to the obligations of candor and good faith imposed by 37 C.F.R. 1.56, the documents listed on the attached PTO-1449 are hereby disclosed.

No representation is intended to be made hereby that any of the cited references establishes, by itself or in combination with other information, a prima facie case of unpatentability of any claim of the present case.

The information disclosure statement transmitted herewith is being filed after three months of the filing date of this national application or the date of entry of the national stage as set forth in

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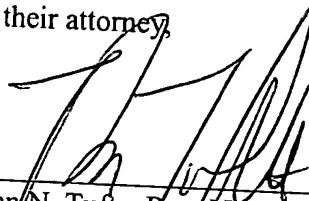
Section 1.491 in an international application or after the mailing date of the first Office Action on the merits, whichever event occurred last but before the mailing date of either a final action under Section 1.113 or a notice of allowance under Section 1.311, whichever occurs first.

Accompanying this transmittal are fees in the amount of \$180.

Respectfully submitted,

Wood et al.

By their attorney,



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Dated: January 14, 2003



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TRANSMITTAL SHEET

The Assistant Commissioner for Patents  
Washington, D.C. 20231

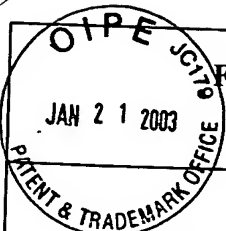
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We are transmitting herewith the attached:

- ☒ [X] Information Disclosure Statement, Form PTO-1449 and 46 cited references.
- ☒ [X] Check in the amount of \$180.00 (IDS after Office Action).
- ☒ [X] Please charge any deficiencies or credit any overpayment in the enclosed fees to Deposit Account No. 50-0413.

By: \_\_\_\_\_

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FORM PTO-1449

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LIST OF PATENTS AND PUBLICATIONS FOR  
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U.S. PATENT DOCUMENTS

TC 1700

Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
	3,577,037	5/1971	Di Pietro			
	3,973,146	8/1976	Arnold et al.			
	4,400,870	8/1983	Islam			
	4,122,479	10/1978	Sugawara et al.			
	4,369,458	1/1983	Thomas et al.			
	4,555,720	11/1985	Redhead			
	4,582,210	4/1986	Morimoto et al.			
	4,701,424	10/1987	Mikkor			
	4,766,316	8/1988	Jungkman			
	4,784,970	11/1988	Solomon			
	4,821,997	4/1989	Zdeblick			
	4,833,102	5/1989	Byrne et al.s			
	4,897,508	1/1990	Mahulikar et al.			
	5,006,711	4/1991	Hanashima et al.			
	5,021,663	1/1997	Hornbeck			
	5,220,838	6/1993	Fung et al.			
	5,264,693	11/1993	Shimabukuro et al.			
	5,318,666	6/1994	Eklind et al.			
	5,366,587	11/1994	Ueda et al.			
	5,397,897	3/1995	Komatsu et al.			
	5,420,419	5/1995	Wood			
	5,521,123	5/1996	Komatsu et al.			
	5,528,452	6/1996	Ko			
	5,581,631	12/1998	Borden et al.			
	5,585,311	12/1996	Ko			



FORM PTO-1449

Atty. Docket No.:  
1100.1138101  
(H16-17400)

Serial No.:  
10/000268

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Filing Date:  
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Group Art:  
1745

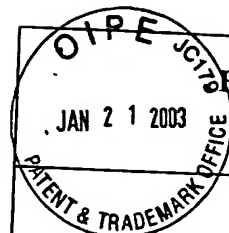
Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
	5,729,019	3/1998	Krafthefer et al.			
	5,736,430	4/1998	Seefeldt et al.			
	5,865,417	2/1999	Harris et al.			
	5,895,233	4/1999	Higashi et al.			
	6,036, 872	3/2000	Wood et al.			
	6,359,333	3/2002	Wood et al.			

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document No.	Date	Country	Translation Yes No
	2121598	12/1983	GB	
	0453372	10/1991	EP	
	0736972	10/1996	EP	

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

	Barth, Philip W., "Silicon Fusion Bonding for Fabrication of Sensors, Actuators and Microstructures", Sensors and Actuators, A21-A23, (1990) pages 919-926.
	Bauer D. et al., "Design and Fabrication of a Thermal Infrared Emitter", Sensors and Actuators A., vol. 55, No. 1, July 15, 1996, pages 57-63.
	Cabuz, C., et al., "Fabrication and packaging of a resonant infrared sensor integrated in silicon", Sensors and Actuators A, 43, May 1994, pages 92-99.
	Henmi, H., et al., "Vacuum packaging for microsensors by glass-silicon anodic bonding", Sensors and Actuators A, 43, May 1994, pages 243-248.
	Kniffen M.L. et al., "Packaging for Silicon Micromachined Accelerometers", International Journal of Microcircuits and Electronic Packaging, vol. 19, No. 1, January 1, 1996, pages 75-86.
	Ko, Wen Hsiung, et al., "Development of a Miniature Pressure Transducer for Biomedical Applications", IEE Transactions on Electron Devices, Vol. ED-26, No. 12, December 1979, pages 1896-1905.



FORM PTO-1449  LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	Atty. Docket No. 1100.1138101 (H16-17400)	Serial No.: 107007,288
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	Mori T. et al., "Vacuum-encapsulated Thermistor bolometer Type Miniature Infrared Sensor". Proceeding of the Workshop on Micro Electro Mehanica Systems (MEM, IOSO, January 25-28, 1994, No. Workshop 7, January 25, 1994, pages 257-262, Institute of Electrical and Electronics Engineers.
	Huang et al., "n-p-n Silicon Lateral Phototransistors for Hybrid Integrated Optical Circuits", IEEE vol. ED-33. No. 4, April 1986, pages 433-441.
	Reichl H., "Packaging and Interconnection of Sensors", Sensors and Actuators A, 25 27 (1991), pages 63-71.
	Senturia Stephen D., et al., "Microsensor Packaging and System Partitioning", Sensors and Actuators, 15 (1988), pages 221-234.
	Tilmans, Harrie A.C., et al., "Micro resonant force gauges", Sensors and Actuator A. 30 (1992) pages 35-53.
	Wolffenbuttel R.F., et al., "Low-temperature silicon wafer-to-wafer bonding using gold at eutectic temperature", Sensors and Actuators A, 43, May 1994, pages 223-229.

EXAMINER:	DATE CONSIDERED:
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.